Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, I²C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	91
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12dg128vpve

Section 3 System Clock Description

Section 4 Modes of Operation

Section 5 Resets and Interrupts

Section 6 HCS12 Core Block Description

List of Figures

Derivative Differences and Document References

Derivative Differences

(Table 0-1) and **(Table 0-2)** show the availability of peripheral modules on the various derivatives. For details about the compatibility within the MC9S12D-Family refer also to engineering bulletin EB386.

Table 0-1 Derivative Differences[1]

Modules	**MC9S12DT128E[3] MC9S12DT128 SC515849[4] SC101161DT[5] SC102205[6]**	**MC9S12DG128E[3] MC9S12DG128 SC515847[4] SC101161DG[5] SC102203[6]**	**MC9S12DJ128E[3] MC9S12DJ128 SC515848[4] SC101161DJ[5] SC102204[6]**	**MC9S12A128**
# of CANs	3	2	2	0
CAN4	✓	✓	✓	✕
CAN1	✓	✕	✕	✕
CAN0	✓	✓	✓	✕
J1850/BDLC	✕	✕	✓	✕
IIC	✓	✓	✓	✓
Byteflight	✕	✕	✕	✕
Package	112 LQFP	112 LQFP/80 QFP[2]	112 LQFP/80 QFP[2]	112 LQFP/80 QFP[2]
Package Code	PV	PV/FU	PV/FU	PV/FU
Mask set	1L40K[3], 3L40K, 0L94R, 4L40K[4], 1L59W[5], 5L40K[6], 2L94R	1L40K[3], 3L40K, 0L94R, 4L40K[4], 1L59W[5], 5L40K[6], 2L94R	1L40K[3], 3L40K, 0L94R, 4L40K[4], 1L59W[5], 5L40K[6], 2L94R	3L40K, 0L94R, 2L94R, 1L59W
Temp Options	M, V, C	M, V, C	M, V, C	C
AEC qualified	Yes	Yes	Yes	No
Notes	An errata exists contact Sales Office	An errata exists contact Sales Office	An errata exists contact Sales Office	An errata exists contact Sales Office

Table 0-2 Derivative Differences for MC9S12DB128[1]

Modules	**MC9S12DB128 SC515846[4] SC102202[6]**	**MC9S12DB128 SC515846[4] SC102202[6]**
# of CANs	2	0
CAN4	✓	✕
CAN1	✕	✕
CAN0	✓	✕
J1850/BDLC	✕	✕
IIC	✕	✕
Byteflight	✓	✓
Package	112 LQFP	80 QFP[2]

  - Digital filtering
  - Programmable rising or falling edge trigger
- Memory
  - 128K Flash EEPROM
  - 2K byte EEPROM
  - 8K byte RAM
- Two 8-channel Analog-to-Digital Converters
  - 10-bit resolution
  - External conversion trigger capability
- Three 1M bit per second, CAN 2.0 A, B software compatible modules
  - Five receive and three transmit buffers
  - Flexible identifier filter programmable as 2 x 32 bit, 4 x 16 bit or 8 x 8 bit
  - Four separate interrupt channels for Rx, Tx, error and wake-up
  - Low-pass filter wake-up function
  - Loop-back for self test operation
- Enhanced Capture Timer
  - 16-bit main counter with 7-bit prescaler
  - 8 programmable input capture or output compare channels
  - Four 8-bit or two 16-bit pulse accumulators
- 8 PWM channels
  - Programmable period and duty cycle
  - 8-bit 8-channel or 16-bit 4-channel
  - Separate control for each pulse width and duty cycle
  - Center-aligned or left-aligned outputs
  - Programmable clock select logic with a wide range of frequencies
  - Fast emergency shutdown input
  - Usable as interrupt inputs
- Serial interfaces
  - Two asynchronous Serial Communications Interfaces (SCI)
  - Two Synchronous Serial Peripheral Interface (SPI)
  - Byteflight
- Byte Data Link Controller (BDLC)

$0040 - $007F ECT (Enhanced Capture Timer 16 Bit 8 Channels)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$007C	TC2H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$007D	TC2H (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$007E	TC3H (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$007F	TC3H (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								

$0080 - $009F ATD0 (Analog to Digital Converter 10 Bit 8 Channel)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0080	ATD0CTL0	Read:	0	0	0	0	0	0	0	0
		Write:								
$0081	ATD0CTL1	Read:	0	0	0	0	0	0	0	0
		Write:								
$0082	ATD0CTL2	Read:	ADPU	AFFC	AWAI	ETRIGLE	ETRIGP	ETRIG	ASCIE	ASCIF
		Write:								
$0083	ATD0CTL3	Read:	0	S8C	S4C	S2C	S1C	FIFO	FRZ1	FRZ0
		Write:								
$0084	ATD0CTL4	Read:	SRES8	SMP1	SMP0	PRS4	PRS3	PRS2	PRS1	PRS0
		Write:								
$0085	ATD0CTL5	Read:	DJM	DSGN	SCAN	MULT	0	CC	CB	CA
		Write:								
$0086	ATD0STAT0	Read:	SCF	0	ETORF	FIFOR	0	CC2	CC1	CC0
		Write:								
$0087	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0088	ATD0TEST0	Read:	0	0	0	0	0	0	0	0
		Write:								
$0089	ATD0TEST1	Read:	0	0	0	0	0	0	0	SC
		Write:								
$008A	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$008B	ATD0STAT1	Read:	CCF7	CCF6	CCF5	CCF4	CCF3	CCF2	CCF1	CCF0
		Write:								
$008C	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$008D	ATD0DIEN	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$008E	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$008F	PORTAD0	Read:	Bit7	6	5	4	3	2	1	BIT 0
		Write:								
$0090	ATD0DR0H	Read:	Bit15	14	13	12	11	10	9	Bit8
		Write:								
$0091	ATD0DR0L	Read:	Bit7	Bit6	0	0	0	0	0	0
		Write:								

Section 2 Signal Description

This section describes signals that connect off-chip. It includes a pinout diagram, a table of signal properties, and detailed discussion of signals. It is built from the signal description sections of the Block User Guides of the individual IP blocks on the device.

2.1 Device Pinout

The MC9S12DT128 and its derivatives are available in a 112-pin low profile quad flat pack (LQFP) and in a 80-pin quad flat pack (QFP). Most pins perform two or more functions, as described in the Signal Descriptions. **Figure 2-1**, **Figure 2-2**, and **Figure 2-3** show the pin assignments for different packages.

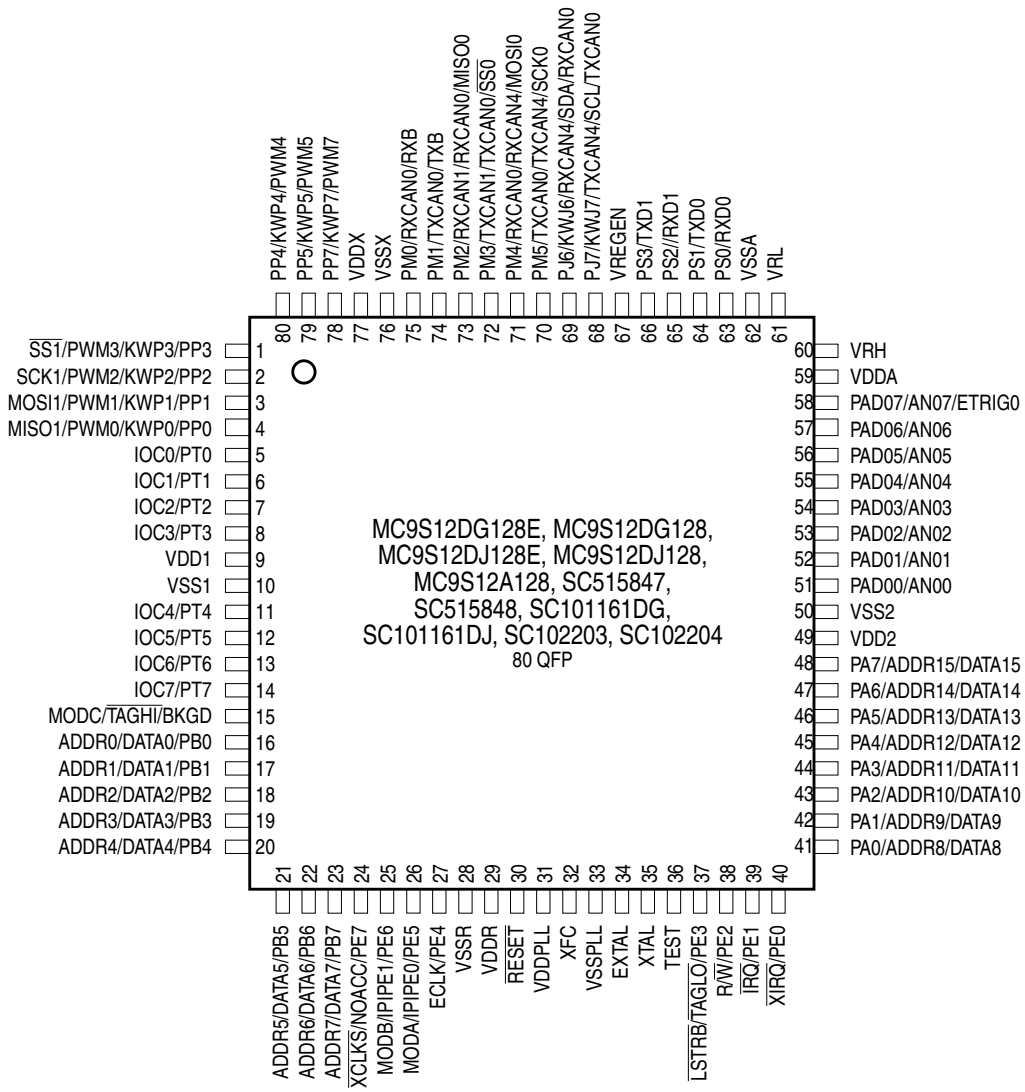


Figure 2-2 Pin Assignments in 80 QFP for MC9S12DG128E, MC9S12DG128, MC9S12DJ128E, MC9S12DJ128, MC9S12A128, SC515847, SC515848, SC101161DG, SC101161DJ, SC102203, and SC102204 Bondout

Figure 23-3 Recommended PCB Layout for 112LQFP Pierce Oscillator

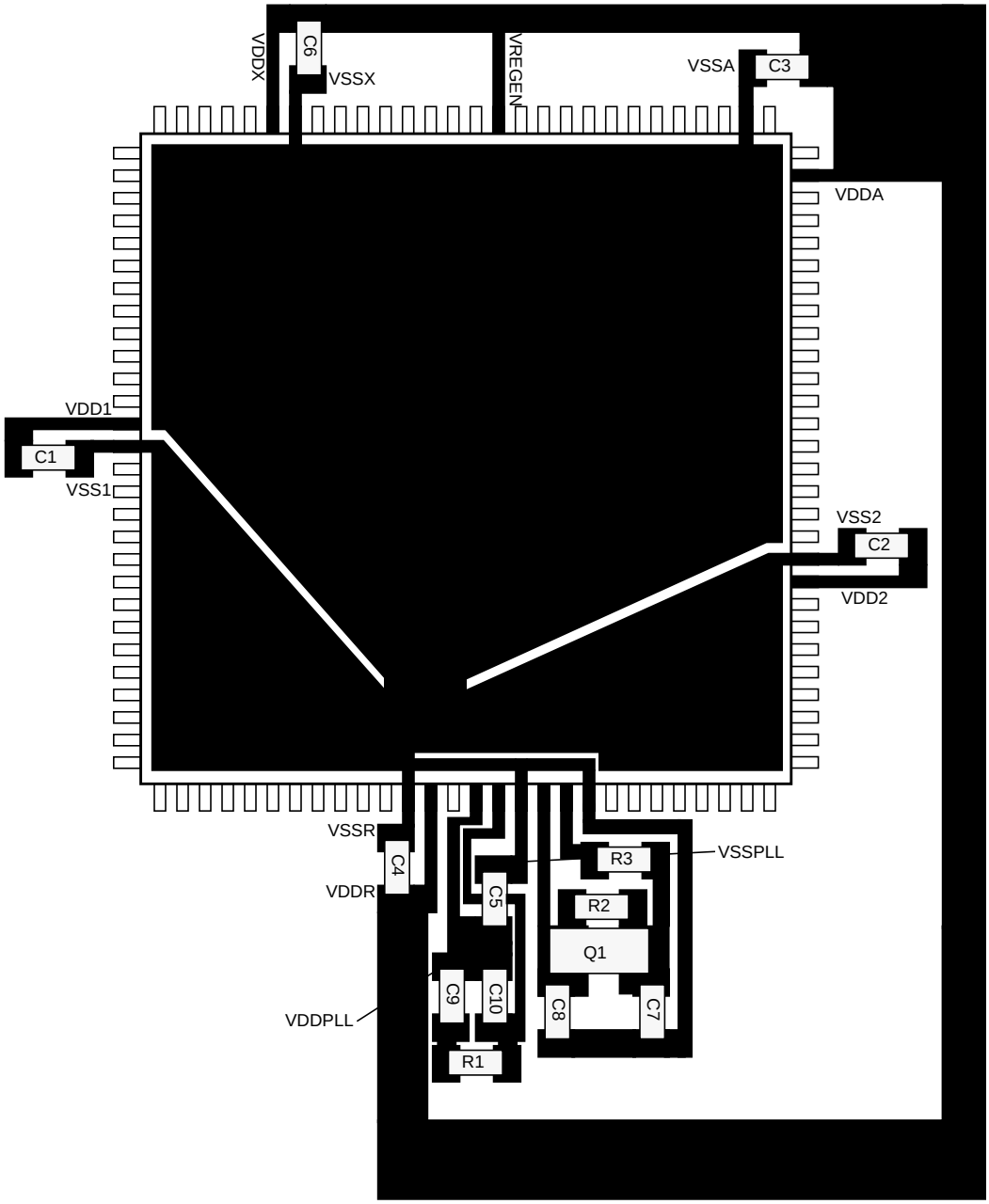


Figure 23-4 Recommended PCB Layout for 80QFP (MC9S12DG128E, MC9S12DG128, MC9S12DJ128E, MC9S12DJ128, MC9S12A128, SC515847, SC515848, SC101161DG, SC101161DJ, SC102203, and SC102204) Pierce Oscillator

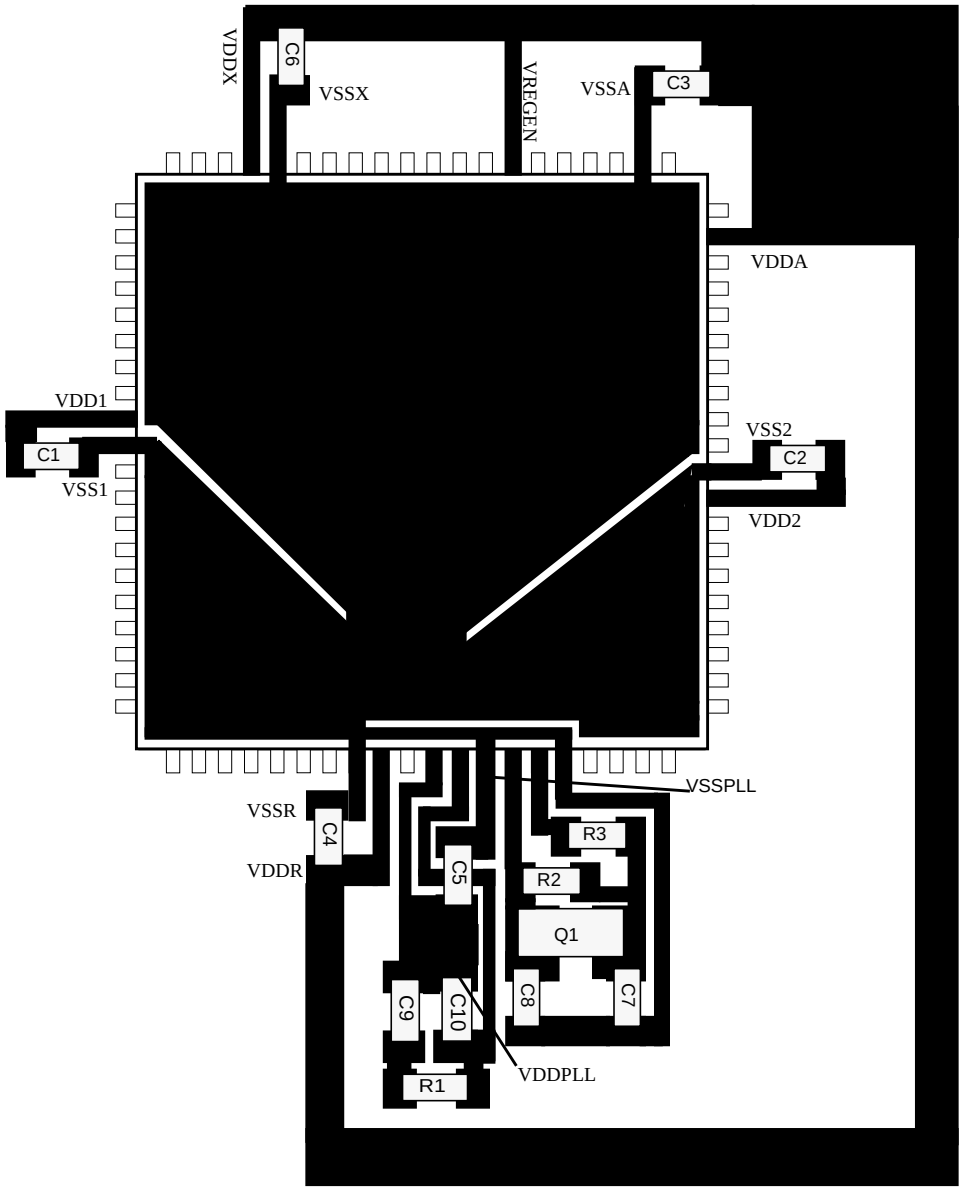
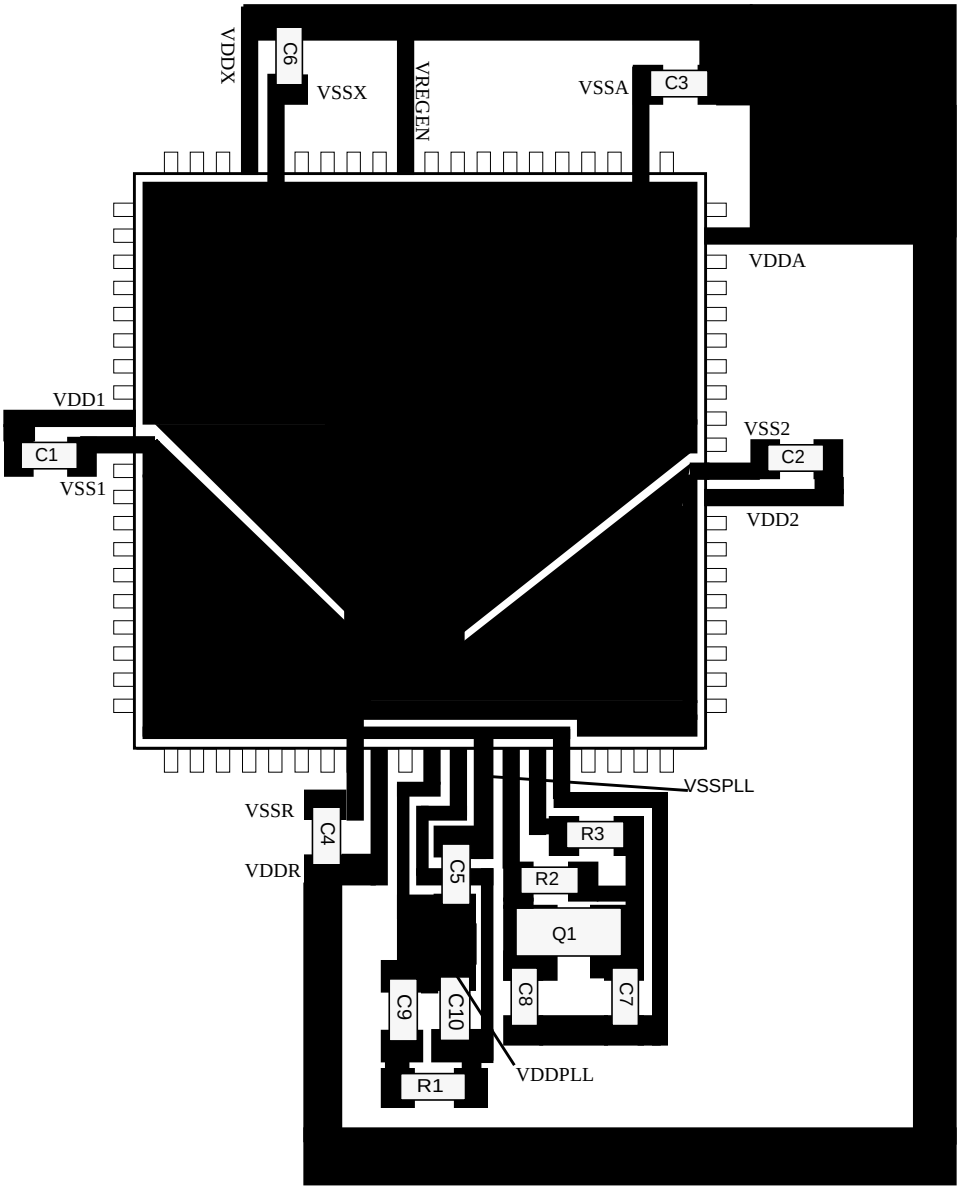


Figure 23-5 Recommended PCB Layout for 80QFP (MC9S12DB128, SC515846, and SC102202) Pierce Oscillator



Appendix A Electrical Characteristics

A.1 General

This introduction is intended to give an overview on several common topics like power supply, current injection etc.

A.1.1 Parameter Classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give the customer a better understanding the following classification is used and the parameters are tagged accordingly in the tables where appropriate.

P:

Those parameters are guaranteed during production testing on each individual device.

C:

Those parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations. They are regularly verified by production monitors.

T:

Those parameters are achieved by design characterization on a small sample size from typical devices. All values shown in the typical column are within this category.

D:

Those parameters are derived mainly from simulations.

A.1.2 Power Supply

The MC9S12DT128 utilizes several pins to supply power to the I/O ports, A/D converter, oscillator, PLL and internal logic.

The VDDA, VSSA pair supplies the A/D converter and the resistor ladder of the internal voltage regulator.

The VDDX, VSSX, VDDR and VSSR pairs supply the I/O pins, VDDR supplies also the internal voltage regulator.

VDD1, VSS1, VDD2 and VSS2 are the supply pins for the digital logic, VDDPLL, VSSPLL supply the oscillator and the PLL.

VSS1 and VSS2 are internally connected by metal.

VDDA, VDDX, VDDR as well as VSSA, VSSX, VSSR are connected by anti-parallel diodes for ESD protection.

Table A-6 5V I/O Characteristics

Conditions are shown in **(Table A-4)** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Input High Voltage	V_{IH}	$0.65*V_{DD5}$	–		V
	T	Input High Voltage	V_{IH}	–	–	V_{DD5} + 0.3	
2	P	Input Low Voltage	V_{IL}	–	–	$0.35*V_{DD5}$	V
	T	Input Low Voltage	V_{IL}	V_{SS5} – 0.3	–	–	V
3	C	Input Hysteresis	V_{HYS}		250		mV
4	P	Input Leakage Current (pins in high ohmic input mode) $V_{in} = V_{DD5}$ or V_{SS5}	I_{in}	-1.0	–	1.0	µA
5	C P	Output High Voltage (pins in output mode) Partial Drive I_{OH} = –2.0mA Full Drive I_{OH} = –10.0mA	V_{OH}	V_{DD5} – 0.8	–	–	V
6	C P	Output Low Voltage (pins in output mode) Partial Drive I_{OL} = +2.0mA Full Drive I_{OL} = +10.0mA	V_{OL}	–	–	0.8	V
7	P	Internal Pull Up Device Current, tested at V_{IL} Max.	I_{PUL}	–	–	–130	µA
8	C	Internal Pull Up Device Current, tested at V_{IH} Min.	I_{PUH}	–10	–	–	µA
9	P	Internal Pull Down Device Current, tested at V_{IH} Min.	I_{PDH}	–	–	130	µA
10	C	Internal Pull Down Device Current, tested at V_{IL} Max.	I_{PDL}	10	–	–	µA
11	D	Input Capacitance	C_{in}		6	–	pF
12	T	Injection current[1] Single Pin limit Total Device Limit. Sum of all injected currents	I_{ICS} I_{ICP}	 –2.5 –25	–	 2.5 25	mA
13	P	Port H, J, P Interrupt Input Pulse filtered [2]	t_{PULSE}			3	µs
14	P	Port H, J, P Interrupt Input Pulse passed [2]	t_{PULSE}	10			µs

NOTES:
1. Refer to **Section A.1.4 Current Injection**, for more details
2. Parameter only applies in STOP or Pseudo STOP mode.

A.1.10 Supply Currents

This section describes the current consumption characteristics of the device as well as the conditions for the measurements.

A.2.3 ATD accuracy

(Table A-10) specifies the ATD conversion performance excluding any errors due to current injection, input capacitance and source resistance.

Table A-10 ATD Conversion Performance

Conditions are shown in **(Table A-4)** unless otherwise noted $V_{REF} = V_{RH} - V_{RL} = 5.12V$. Resulting to one 8 bit count = 20mV and one 10 bit count = 5mV $f_{ATDCLK} = 2.0MHz$							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	10-Bit Resolution	LSB		5		mV
2	P	10-Bit Differential Nonlinearity	DNL	–1		1	Counts
3	P	10-Bit Integral Nonlinearity	INL	–2.5	±1.5	2.5	Counts
4	P	10-Bit Absolute Error[1]	AE	-3	±2.0	3	Counts
5	P	8-Bit Resolution	LSB		20		mV
6	P	8-Bit Differential Nonlinearity	DNL	–0.5		0.5	Counts
7	P	8-Bit Integral Nonlinearity	INL	–1.0	±0.5	1.0	Counts
8	P	8-Bit Absolute Error(1)	AE	-1.5	±1.0	1.5	Counts

NOTES:
1. These values include the quantization error which is inherently 1/2 count for any A/D converter.

For the following definitions see also **Figure A-1**.

Differential Non-Linearity (DNL) is defined as the difference between two adjacent switching steps.

$$DNL(i) = \frac{V_i - V_{i-1}}{1LSB} - 1$$

The Integral Non-Linearity (INL) is defined as the sum of all DNLs:

$$INL(n) = \sum_{i=1}^{n} DNL(i) = \frac{V_n - V_0}{1LSB} - n$$

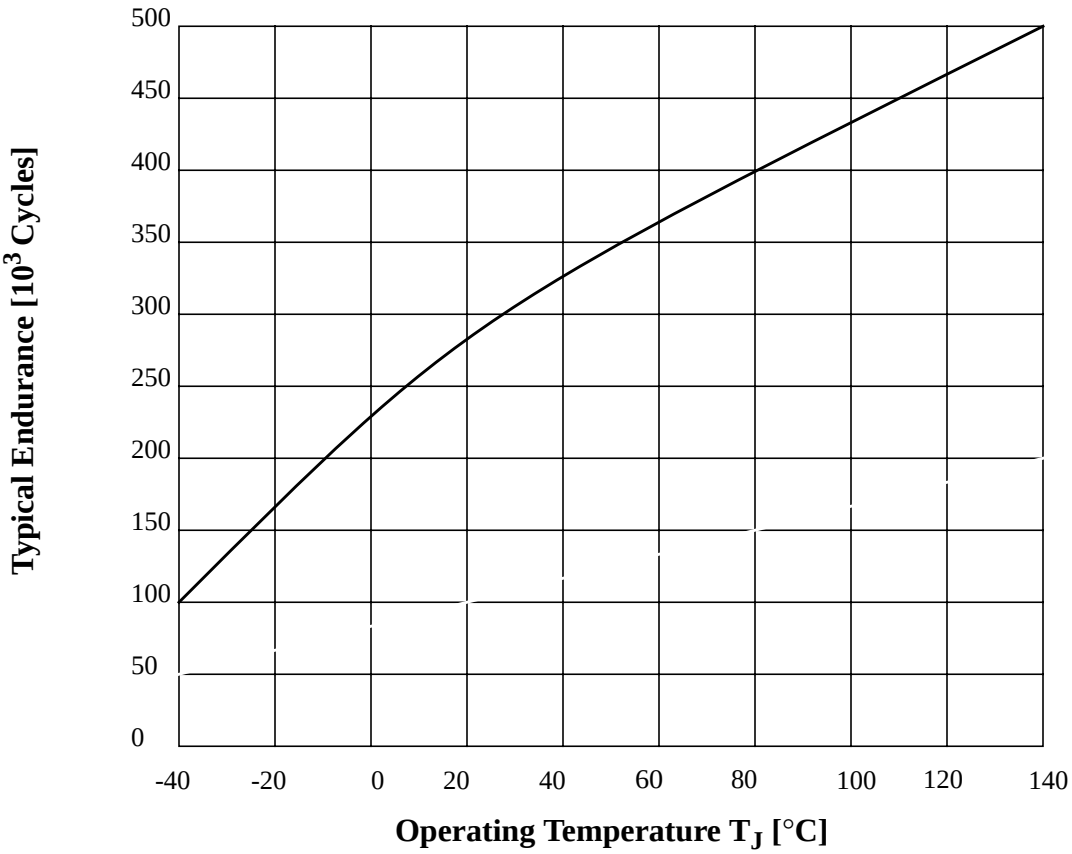
A.3.2 NVM Reliability

The reliability of the NVM blocks is guaranteed by stress test during qualification, constant process monitors and burn-in to screen early life failures.

The failure rates for data retention and program/erase cycling are specified at the operating conditions noted.

The program/erase cycle count on the sector is incremented every time a sector or mass erase event is executed.

Figure A-2 Typical Endurance vs Temperature



Flash
------ EEPROM

And finally the frequency relationship is defined as

$$n = \frac{f_{VCO}}{f_{ref}} = 2 \cdot (synr + 1) \quad = 50$$

With the above values the resistance can be calculated. The example is shown for a loop bandwidth f_C=10KHz:

$$R = \frac{2 \cdot \pi \cdot n \cdot f_C}{K_\Phi} \quad = 2*\pi*50*10kHz/(316.7Hz/\Omega)=9.9k\Omega =\sim 10k\Omega$$

The capacitance C_s can now be calculated as:

$$C_s = \frac{2 \cdot \zeta^2}{\pi \cdot f_C \cdot R} \approx \frac{0.516}{f_C \cdot R};(\zeta = 0.9) \quad = 5.19nF =\sim 4.7nF$$

The capacitance C_p should be chosen in the range of:

$$C_s/20 \le C_p \le C_s/10 \quad C_p = 470pF$$

A.5.3.2 Jitter Information

The basic functionality of the PLL is shown in **Figure A-3**. With each transition of the clock f_{cmp}, the deviation from the reference clock f_{ref} is measured and input voltage to the VCO is adjusted accordingly.The adjustment is done continuously with no abrupt changes in the clock output frequency. Noise, voltage, temperature and other factors cause slight variations in the control loop resulting in a clock jitter. This jitter affects the real minimum and maximum clock periods as illustrated in **Figure A-4**.

A.7.2 Slave Mode

Figure A-8 and **Figure A-9** illustrate the slave mode timing. Timing values are shown in **(Table A-19)**.

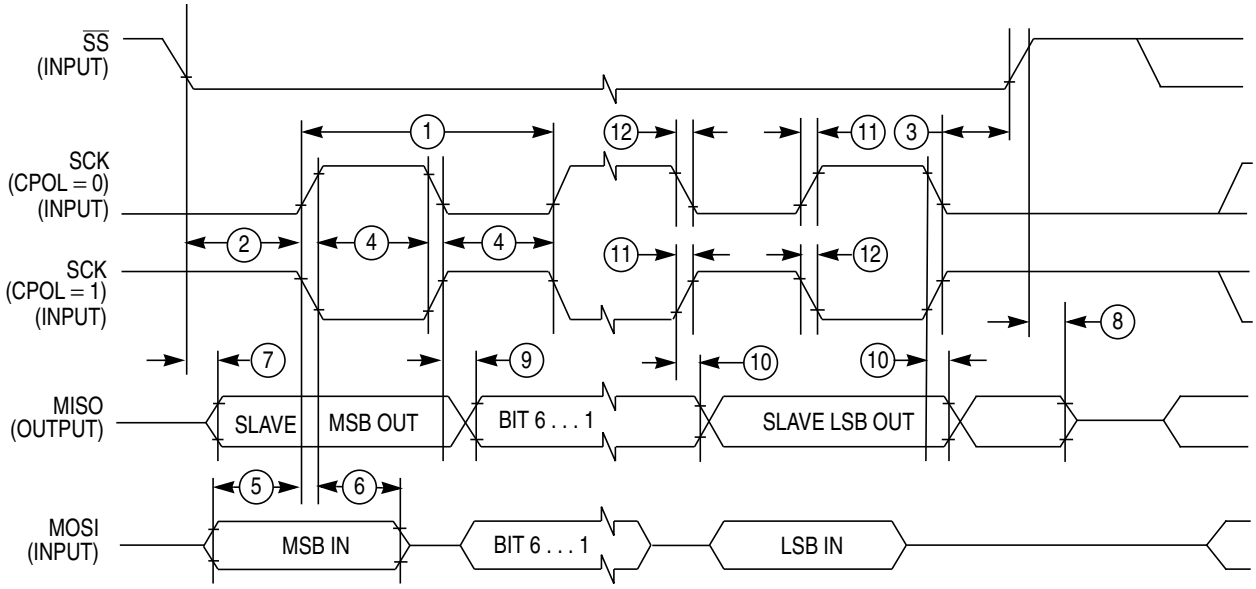


Figure A-8 SPI Slave Timing (CPHA = 0)

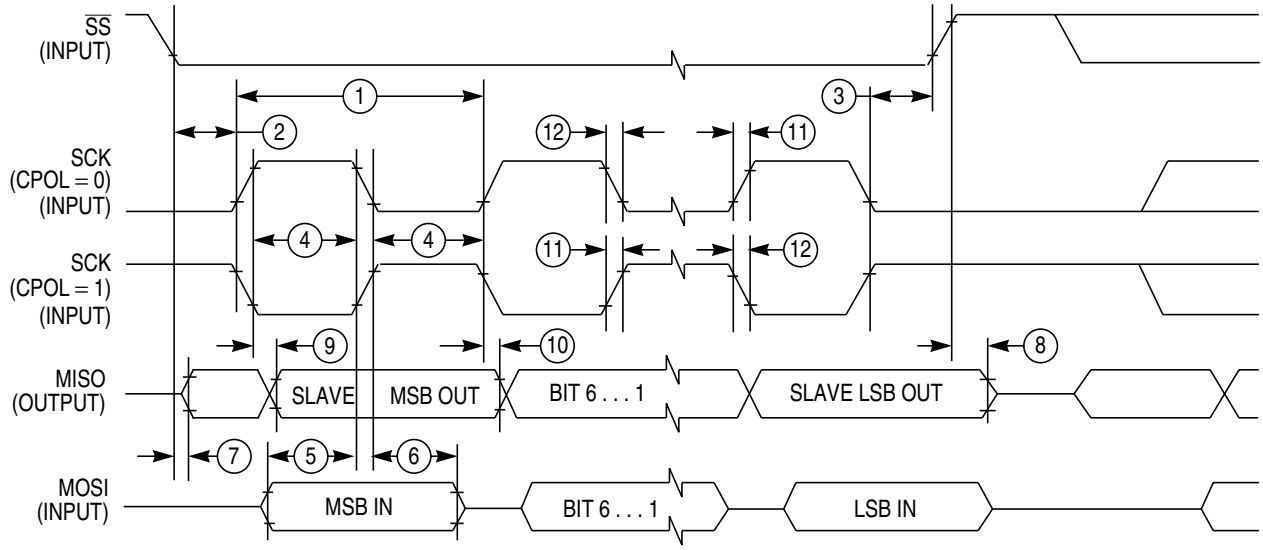


Figure A-9 SPI Slave Timing (CPHA =1)

A.8 External Bus Timing

A timing diagram of the external multiplexed-bus is illustrated in **Figure A-10** with the actual timing values shown on table **(Table A-20)**. All major bus signals are included in the diagram. While both a data write and data read cycle are shown, only one or the other would occur on a particular bus cycle.

A.8.1 General Multiplexed Bus Timing

The expanded bus timings are highly dependent on the load conditions. The timing parameters shown assume a balanced load across all outputs.